

EAST - Inference Search

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	23	((solder) near8 (void or voided or bubble or air) near8 (reflow\$4 or flow\$4)).clm.	US-PGPUB	OR	ON	2006/02/28 17:27
L8	7	((((thermal or thermally or heat) near (interface or adhesive) or tim) near8 (void or voided or bubble)).clm.	US-PGPUB	OR	ON	2006/02/28 17:30
L9	5	((((thermal or thermally or heat) near (interface or adhesive) or tim) near8 (stress\$3 or strain\$3)).clm.	US-PGPUB	OR	ON	2006/02/28 17:29
L10	5	((chip or die) near (back or backside) near5 solder).clm.	US-PGPUB	OR	ON	2006/02/28 17:30
L11	3	((((lid or cover or heatsink or heat near sink or heat near spreader) near (interface or adhesive) or tim) near8 (void or voided or bubble)).clm.	US-PGPUB	OR	ON	2006/02/28 17:31
L12	0	((((lid or cover or heatsink or heat near sink or heat near spreader) near (interface or adhesive) or tim) near8 (stress\$4 or strain\$4)).clm.	US-PGPUB	OR	ON	2006/02/28 17:31

EAST - text search notes

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	135	257/E23.11.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:19
L5	249	257/E23.109.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:19
L3	1047	257/E23.101.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:16
S55	280	257/707.ccls. and (tim or (heat or thermal) near2 (interface or adhesive or adhesion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:08
L4	257	257/E23.101.ccls. and (tim or (heat or thermal) near2 (interface or adhesive or adhesion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:08
L2	339	257/E23.087.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 17:08
S54	69	257/706.ccls. and (tim or (heat or thermal) near2 (interface or adhesive or adhesion)) near10 (wett\$4 or stress\$3 or strain\$3 or void or voiding or voided or bubble or air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 11:24
S52	109	257/704.ccls. and (tim or (heat or thermal) near2 (interface or adhesive or adhesion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 11:23
S49	227	438/122.ccls. and (tim or (heat or thermal) near2 (interface or adhesive or adhesion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 11:18

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S51	253	438/760.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 11:11
S50	257	438/117.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 11:11
S48	760	438/122.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 11:03
S47	142	(tim or thermal near interface or (interface or adhesive or attach\$4) near2 (heat near spreader or heat near slug or heat near sink or heatsink or cover or lid)) near15 (wett\$4 or nonwett\$4 or solderability or solderable)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 10:56
S43	16	(tim or thermal near interface or (interface or adhesive or attach\$4) near2 (heat near spreader or heat near slug or heat near sink or heatsink)) near10 (void or voided or bubble or gap or interval or vacancy or hole or open or air) near15 (stress\$3 or strain\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 10:21
S46	33	((interface or adhesive or attach\$4) near4 (cover or lid)) near5 (void or voided or bubble or gap or interval or vacancy or hole or open or air) near15 (stress\$3 or strain\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 10:19
S45	0	((interface or adhesive or attach\$4) near2 (cover or lid)) near10 (void or voided or bubble or gap or interval or vacancy or hole or open or air) near15 (wett\$4 or solderable or solderability or nonwett\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 10:18
S44	10	(tim or thermal near interface or (interface or adhesive or attach\$4) near2 (heat near spreader or heat near slug or heat near sink or heatsink)) near10 (void or voided or bubble or gap or interval or vacancy or hole or open or air) near15 (wett\$4 or solderable or solderability or nonwett\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 10:18

EAST Search History

S41	100	(tim or thermal near interface) near5 (void or voided or bubble or (air or compliant) near (gap or interval))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 10:09
S40	65	(tim or thermal near interface) near5 (void or voided)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 09:39
S39	108	solder near10 (gaps or void or bubble or opening) near10 (wettab\$4 or wetting or nonwett\$7) same (reflow\$3 or flow\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 17:02
S38	203	solder near4 (gaps or void or bubble or opening) same (wettab\$4 or wetting or nonwett\$7) same (reflow\$3 or flow\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 17:02
S37	39	(sheet or preform or preformed or pre-form\$2 or solder) near10 (pattern\$4) near10 (wettab\$5 or wetting) near10 (reflow\$4 or re-flow\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 17:00
S36	5	(solder) near8 (sheet or preform or preformed or pre-form\$2) near15 (pattern\$4) near15 (wettab\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:27
S35	3	(solder) near3 (sheet or preform or preformed or pre-form\$2) near15 (pattern\$4) near15 (wettab\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:27
S34	217	(solder) near3 (sheet or preform or preformed or pre-form\$2) near8 (pattern\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:26
S33	147	(solder) near8 (wettab\$4) near8 (pattern\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:26
S32	139	solder near4 flux\$4 near5 solvent and (solder near ball or solder near bump or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:14

EAST Search History

S31	67	(chip or die or integrated adj circuit) and (lid or cover or heatsink or heat near sink) same (solder\$4) same (non-wett\$4 or nonwett\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:54
S30	263	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (lid or cover or heatsink or heat near sink) near5 (solder\$4) near10 (openings or voids or holes or apertures or missing or absent or air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:43